



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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Email & Skype: info@chipsmall.com Web: www.chipsmall.com

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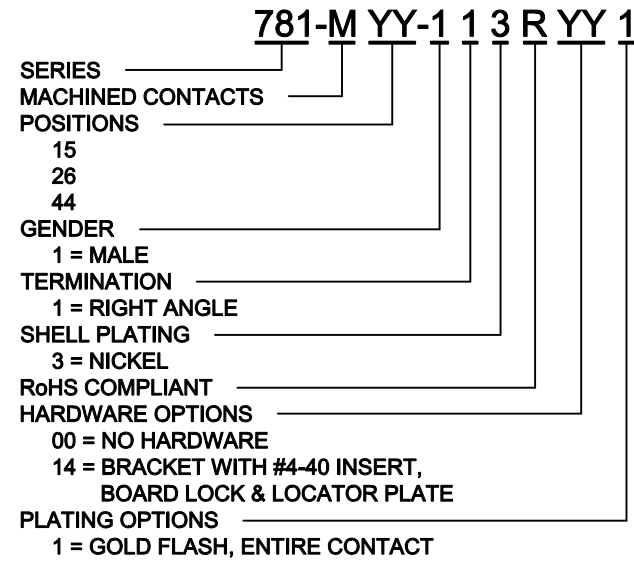
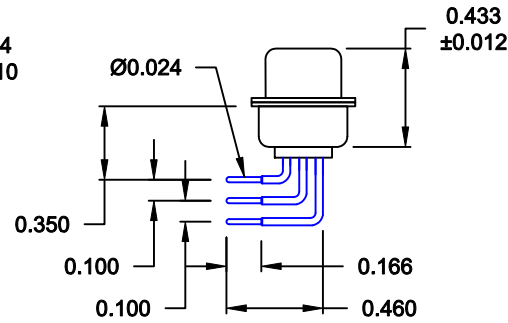
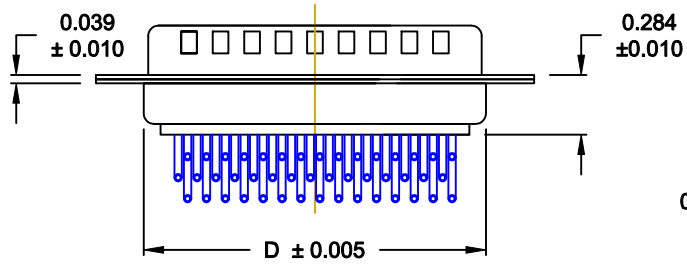
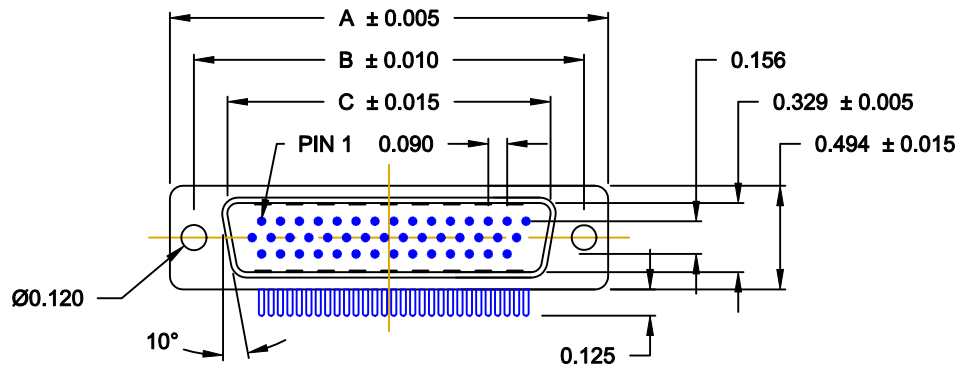
DESCRIPTION: MALE - HIGH DENSITY - MACHINED CONTACTS - RIGHT ANGLE

**MATERIAL:**

SHELL: STEEL MATERIAL, NICKEL FINISH  
 INSULATOR: PA6T=260°C, UL 94V-0 RATED, BLACK  
 CONTACT MATERIAL: BRASS  
 CONTACT FINISH: SELECTIVE GOLD FINISHED  
 SEALING MATERIAL: F08 FLEXIBLE ADHESIVE

**ELECTRICAL:**

CONTACT CURRENT RATING: 5 AMPS  
 CONTACT RESISTANCE: 30 Milliohms Max.  
 DIELECTRIC WITHSTANDING VOLTAGE: 1,000VAC Min.  
 INSULATION RESISTANCE: 5,000 Megohms Min.  
 TEMPERATURE RATING: -55° ~ +105° C



DIMENSIONS (IN.)				
No. OF PINS	A	B	C	D
15	1.213	0.984	0.666	0.759
26	1.541	1.312	0.994	1.083
44	2.088	1.852	1.534	1.625

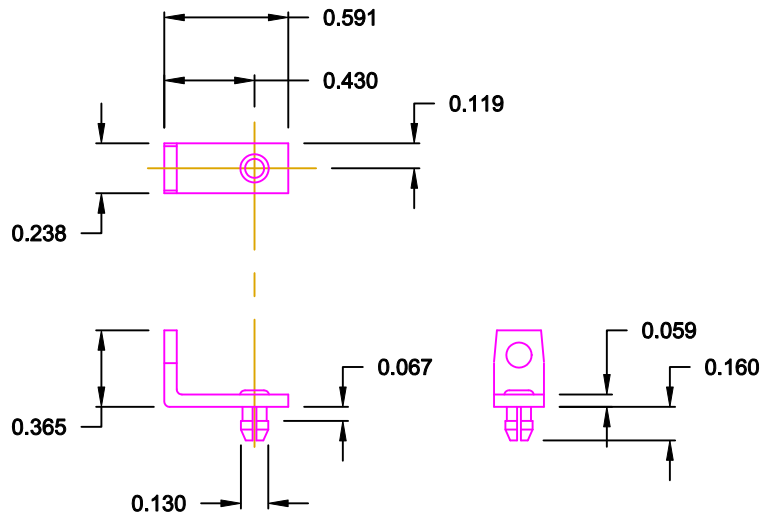
**MEETS IP67 STANDARDS**

(SEE PAGE 4 FOR SEALING DETAILS)

**DO NOT SCALE FROM DRAWING**

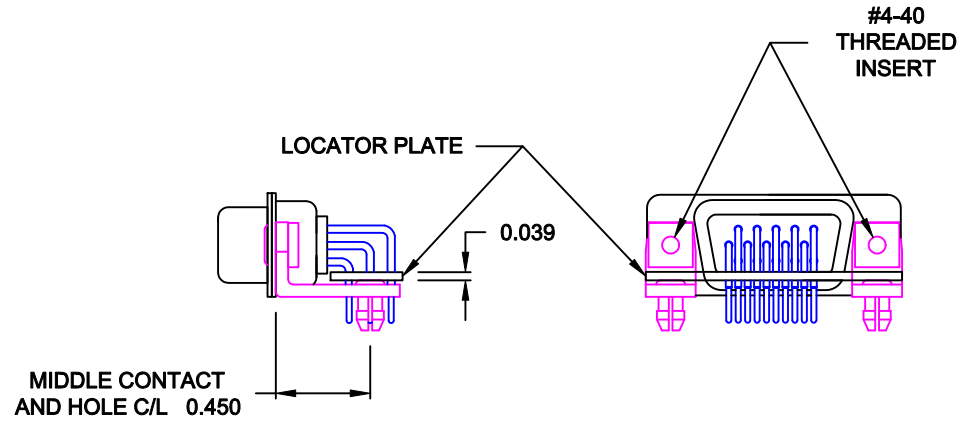
**RoHS COMPLIANT**

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			CHECKED:	DATE:
<b>NorComp</b>	SCALE: <b>1:1</b>	SHEET <b>1</b> OF <b>4</b>	REV <b>3</b>	
	DWG NO. <b>781-MYY-113RYY1</b>			



**MOUNTING BRACKET  
WITH BOARD LOCK**

HARDWARE OPTION 14



**BRACKETS MOUNTED ON CONNECTOR  
WITH LOCATOR PLATE**

HARDWARE OPTION 14

**FOR CLARITY  
HIDDEN LINES  
NOT SHOWN**

**MATERIAL: COLD ROLLED STEEL**

**PLATING: CLEAR ZINC**



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DRAWN:  
**PAM JENKINS**

DATE:  
**11-28-05**

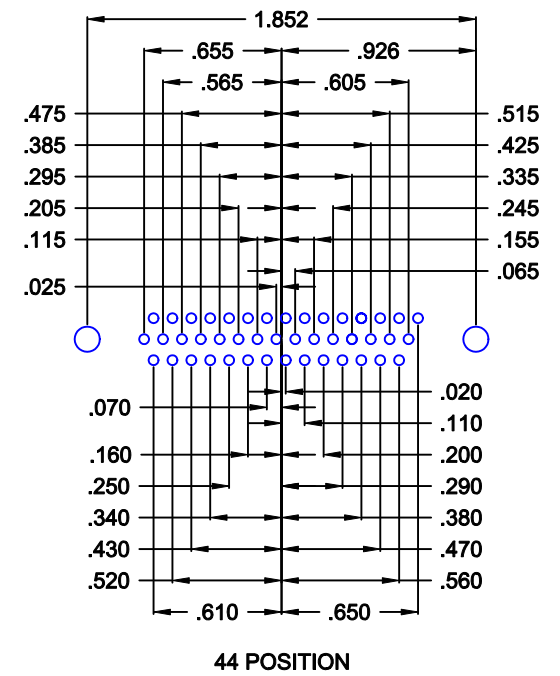
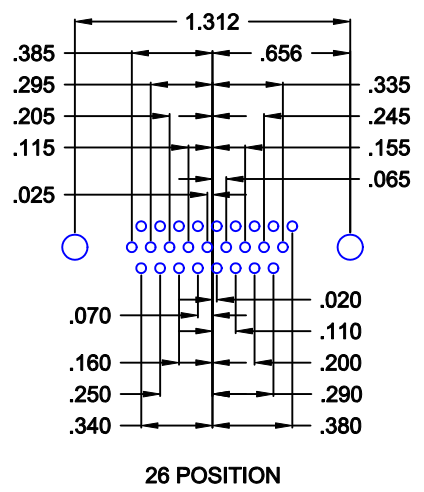
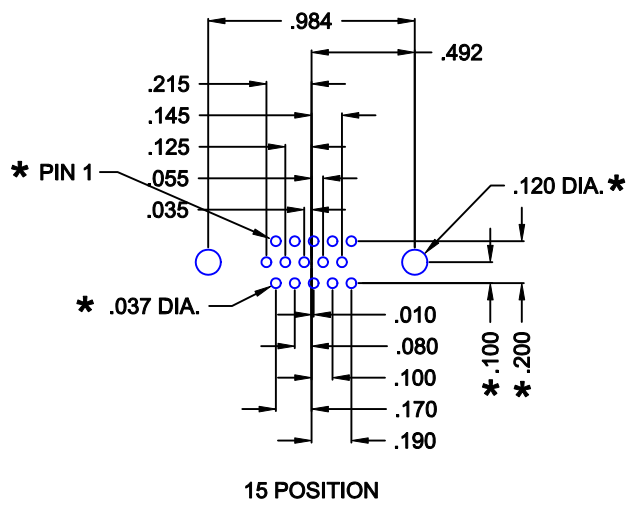
CHECKED:

DATE:

**NorComp**


SCALE: **1:1** SHEET **2** OF **4** REV **3**

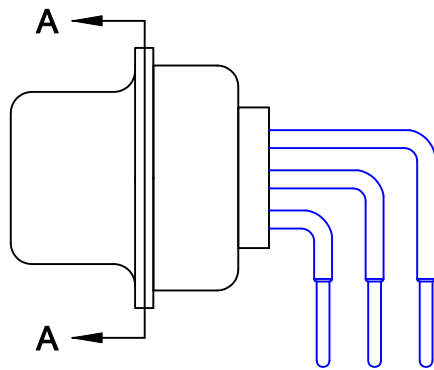
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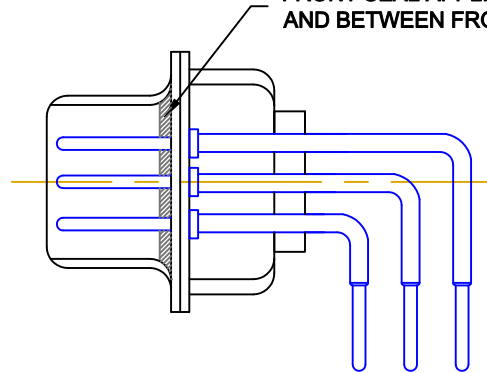
\* TYP. ON ALL SIZES

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			CHECKED:	DATE:
<b>NorComp</b>		SCALE: <b>1 : 1</b>	SHEET <b>3</b>	OF <b>4</b>
		DWG NO. <b>781-MYY-113RYY1</b>		




FRONT SEAL APPLIED OVER INSULATOR AND BETWEEN FRONT & REAR SHELLS



DETAIL A-A

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			CHECKED:	DATE:	
<h1>NorComp</h1>			SCALE: <b>2.5 : 1</b>	SHEET <b>4</b> OF <b>4</b>	REV <b>3</b>
			DWG NO. <b>781-MYY-113RYY1</b>		